

Marked-Up Copy

Serial No: 09/119,626

Amendment Filed on: 4/12/02

IN THE CLAIMS

16. (Once Amended) A chip part device comprising:

a circuit board including a board main body and a conductive layer formed on said board main body, said conductive layer having a plurality of bonding areas defined by a conductive pattern; and

a chip element mounted on said circuit board, and having a plurality of bump electrodes which are joined with said bonding areas by ultrasonic bonding,

wherein said circuit board includes at least two grooves defined by said conductive pattern, and located approximate to one of said bonding areas to put the bonding area therebetween, and wherein said at least two grooves do not extend into said board main body.

19. (New)

20. (New)

21. (New)

22. (New)

23. (New)

24. (New)

25. (New)

26. (New)